

Amendments to the Specification

IN THE WRITTEN DESCRIPTION

Please replace the paragraph beginning at page 1, line 17, with the following rewritten paragraph:

When the plating is carried out on resin molded articles such as an ABS resin, an etching step of roughing the surface of the resin molded articles is conventionally essential to enhance the adhering strength after the removal step of fat. For example, when an ABS resin molded article and a polypropylene molded article are plated, a bath of chromic acid (a ~~mix~~mixed solution of chromium (III) oxide and sulfuric acid) is used after the removal step of fat, and an etching treatment is required to be carried out at 65 to 70°C for 10 to 15 minutes.

Please replace the paragraph beginning at page 4, line 6, with the following rewritten paragraph:

As means for achieving the additional object, the present invention provides a method of producing a plated resin molded article wherein the aforementioned plated resin molded article is produced by plating metal on the surface of the thermoplastic resin molded article, the method comprising the step of:

contact-treatment of the thermoplastic resin molded article with an acid or base that does not contain a heavy metal, as a treatment preceding a metal plating step, and wherein a step of etching with a heavy metal-containing acid is not included.

Please replace the paragraph beginning at page 5, line 2, with the following rewritten paragraph:

The method according to the present invention of producing plated resin molded articles will be described hereinbelow in combination with a description of the plated resin molded articles according to the present invention. The

method according to the present invention of producing plated resin molded articles is not particularly limited as long as a step of bringing the thermoplastic resin molded article into contact with an acid or base that does not contain a heavy metal (referred to below as the "acid or base contact treatment step") is included as a treatment preceding the metal plating step and a step of etching with a heavy metal-containing acid is not included. Some of the following process steps can be omitted and other known plating steps can be added.

Please replace the paragraph beginning at page 8, line 1, with the following rewritten paragraph:

The olefin-based resin is a polymer in which a mono-olefin having 2 to 8 carbons is a main monomer component, and there can be included one kind or more polymers which are selected from a low density polyethylene, a high density polyethylene, a linear low density polyethylene, a polypropylene, an ethylene-propylene random copolymer, an ethylene-propylene block copolymer, a polymethylpentene, a poly(1-butene), and a modified product thereof and the like. Among these, a polypropylene and an acid-modified polypropylene are preferable.

Please replace the paragraph beginning at page 10, line 20, with the following rewritten paragraph:

Component (D) is a surfactant and/or coagulant. The surfactant may be a surfactant that remains in the resin from the surfactant (emulsifying agent) used when emulsion polymerization is employed to produce component (A) or (B), or may be a surfactant that is specifically added to component (A) or (B) when a production method is used that does not employ surfactant, such as bulk polymerization. The adhesive strength of the metal plating layer is increased by the presence of component (D) in the thermoplastic resin molded article.

Please replace the paragraph beginning at page 12, line 12, with the following rewritten paragraph:

Triphenyl phosphate, tricresyl phosphate, trixylenyl phosphate, tris(isopropylphenyl) phosphate, tris(o- or p-phenylphenyl) phosphate, trinaphthyl phosphate, cresyl diphenyl phosphate, xylenyl diphenyl phosphate, ~~diphenyl (2-ethylhexyl) phosphate~~, di(isopropylphenyl) phenyl phosphate, o-phenylphenyl dicresyl phosphate, tris(2,6-dimethylphenyl) phosphate, condensed phosphate esters such as tetraphenyl m-phenylene diphosphate, tetraphenyl p-phenylene diphosphate, phenyl resorcinol polyphosphate, bisphenol A-bis(diphenyl phosphate), bisphenol A-polyphenyl phosphate or dipyrocatechol hypodiphosphate.

Please replace the paragraphs beginning at page 14, line 2, with the following rewritten paragraphs:

The thermoplastic resin molded article is subjected to a treatment of the removal of fat. The treatment of the removal of fat is carried out by a surfactant aqueous solution which contains an alkali such as sodium hydroxide and sodium carbonate, or acids such as sulfuric acid and carbonic acid. In the present invention, after the treatment of the removal of fat, the step can be transferred to other steps, and an etching treatment by an acid containing heavy metals such as chromic acid or potassium permanganate (in the present invention, such as chromium or manganese) which becomes a roughening treatment for enhancing the adhering strength of a plating layer is unnecessary.

(The acid or base contact treatment step)

After the treatment of the removal of fat, the thermoplastic resin molded article is then subjected to the contact treatment with an acid or base. The non-heavy metal acid or base used in this step is preferably present in a low concentration, preferably less than 4.0 normal, more

preferably 3.5 normal or less, and even more preferably 3.0 normal or less.

Please replace the paragraph beginning at page 15, line 21, with the following rewritten paragraph:

The treatment by a catalyst imparting liquid is ~~immersed~~immersion, for example, in a 35% hydrochloric acid solution (10 to 20 mg $l^{-1}$ ) of stannic chloride (20 to 40 gl $^{-1}$ ) for about 1 to 5 minutes at room temperature. The treatment by an activating liquid is ~~immersed~~immersion in a 35% hydrochloric acid solution (3 to 5 mg $l^{-1}$ ) of palladium chloride (0.1 to 0.3 gl $^{-1}$ ) for about 1 to 2 minutes at room temperature.

Please replace the paragraph beginning at page 20, line 3, with the following rewritten paragraph:

D-1: ~~α-Olefin~~olefin sulfonate (LIPOLAN PB800 manufactured by LION Corporation)

Please replace the paragraph beginning at page 20, line 21, with the following rewritten paragraph:

(iii) Catalyst imparting step: The test piece was immersed in a ~~mix~~mixed aqueous solution (a solution temperature of 25°C) of 150 ml/L of 35% by weight of hydrochloric acid and 40 ml/L aqueous solution of Catalyst C (manufactured by OKUNO Pharmaceuticals Co., Ltd.) for 3 minutes.

Please replace the paragraph beginning at page 21, line 17, with the following rewritten paragraph:

(viii) ~~Electroplate~~Electroplating step of copper: The test piece was immersed in a plating bath having the under-mentioned composition (a solution temperature of 25°C), and electroplate was carried out for 120 minutes.

(Composition of plating bath)

Copper sulfate (CuSO $_4 \cdot 5H_2O$ ): 200 g/L

Sulfuric acid (98%): 50 g/L

Chlorine ion ( $\text{Cl}^-$ ): 5 ml/L

TOP LUCINA 2000 MU (manufactured by OKUNO Pharmaceuticals Co., Ltd.): 5 ml/L

TOP LUCINA 2000 A (manufactured by OKUNO Pharmaceuticals Co., Ltd.): 0.5 ml/L